

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-22 (canceled).

Claim 23 (currently amended): [[The]] A method of claim 2 for fabricating a wiring substrate comprising the steps of:

forming an insulating film on a metal base having openings on the metal base at positions corresponding to metal bumps to be formed later;

forming at least one layer of wiring on the base made of a metal through the insulating film, the layer of wiring having a wiring film formed thereon by electroplating; and

selectively etching the base,

wherein the wiring layer formed through the insulating film is in contact with the metal base.

Claim 24 (currently amended): The method of claim [[2]] 25, wherein the wiring layer formed through the insulating film is in contact with the metal base at the openings in the

insulating film and in contact with the insulating film where there are no openings in the insulating film.

Claim 25 (currently amended): The method of claim [[2]] 23, wherein the wiring layer is formed in the area of the openings on the insulating film so as to be formed through the film in contact with the base.

Claim 26 (canceled).

Claim 27 (currently amended): [[The]] A method of claim 2 for fabricating a wiring substrate comprising the steps of:

forming an insulating film on a metal base having openings on the metal base at positions corresponding to metal bumps to be formed later;

forming at least one layer of wiring on the base made of a metal through the insulating film, the layer of wiring having a wiring film formed thereon by electroplating; and

selectively etching the base,

wherein the wiring film ~~can function~~ functions as an etching stopper.